

### ABSTRACT OF THE DISCLOSURE

A semiconductor chip semiconductor device of the present invention is capable of obtaining a high-quality bare chip (HQC) easily and can retain quality without being affected by the surrounding environment. Electrodes  
5 formed on the surface of a first resin sealed package for sealing a semiconductor chip are connected to the electrodes of the semiconductor chip and each electrode comprises a mounting area to be connected to an object to be mounted and a testing area for connecting testing equipment.